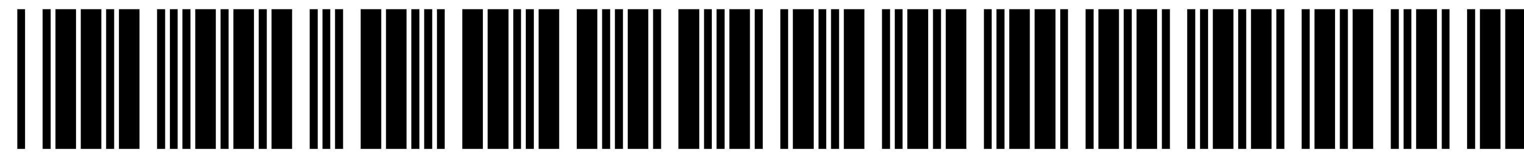

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**Doan et al.**

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(54) **SEMICONDUCTOR PROCESSING METHODS OF REMOVING CONDUCTIVE MATERIAL**

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(52) **U.S. Cl.** ............................ **451/41**; 451/60; 451/287

(58) **Field of Search** ................................ 451/41, 60, 5, 451/285–289, 446, 93, 36, 37, 39

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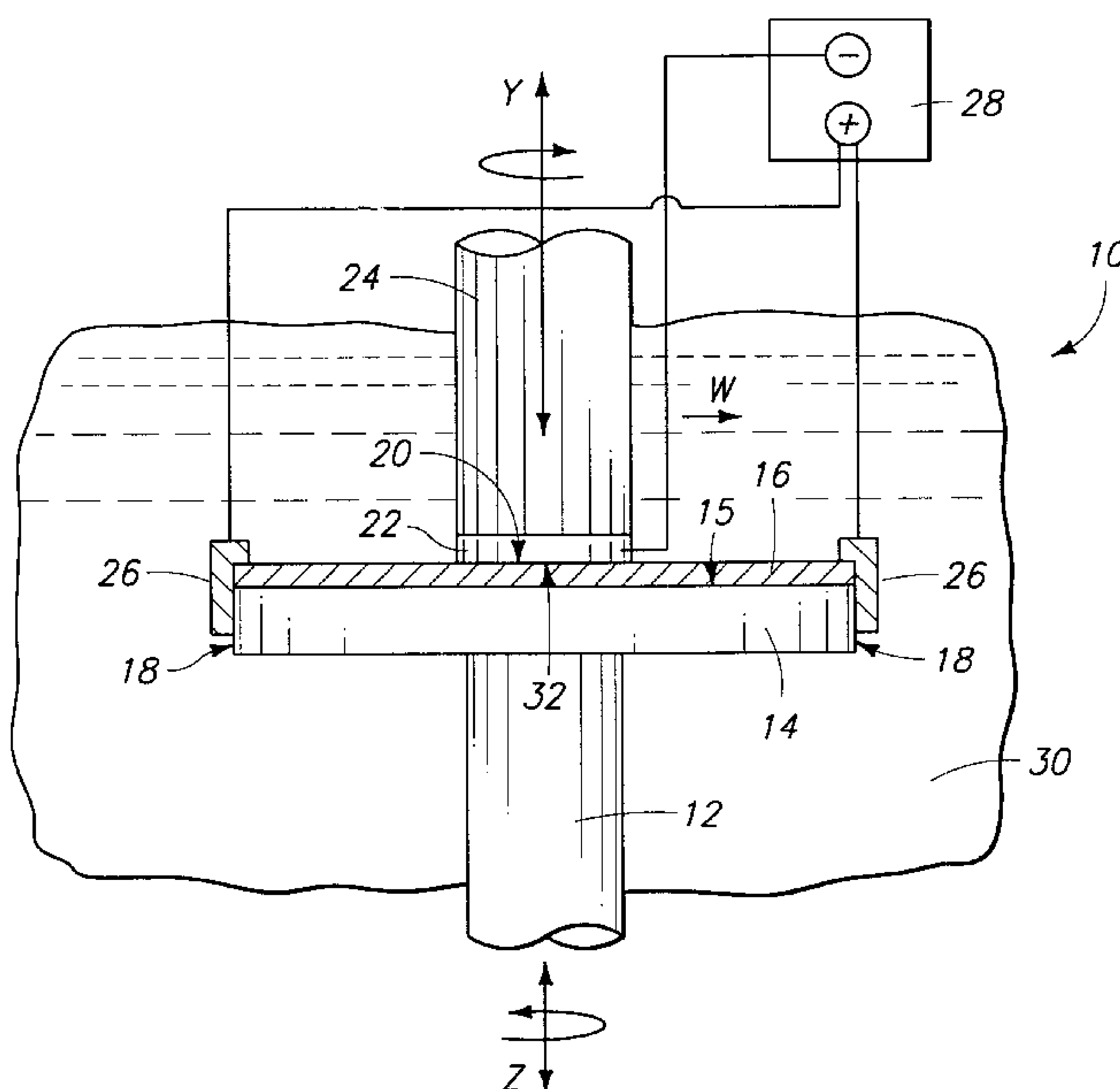
(57) **ABSTRACT**

The invention includes a semiconductive processing method of electrochemical-mechanical removing at least some of a conductive material from over a surface of a semiconductor substrate. A cathode is provided at a first location of the wafer, and an anode is provided at a second location of the wafer. The conductive material is polished with the polishing pad polishing surface. The polishing occurs at a region of the conductive material and not at another region. The region where the polishing occurs is defined as a polishing operation location. The polishing operation location is displaced across the surface of the substrate from said second location of the substrate toward said first location of the substrate. The polishing operation location is not displaced from said first location toward said second location when the polishing operation location is between the first and second locations. The invention also includes a semiconductor processing method of removing at least some of a conductive material from over a surface of a semiconductive material wafer. A polishing pad is displaced across an upper surface of the wafer from a central region of the wafer toward a periphery of the wafer, and is not displaced from the periphery to the central region.

**38 Claims, 2 Drawing Sheets**



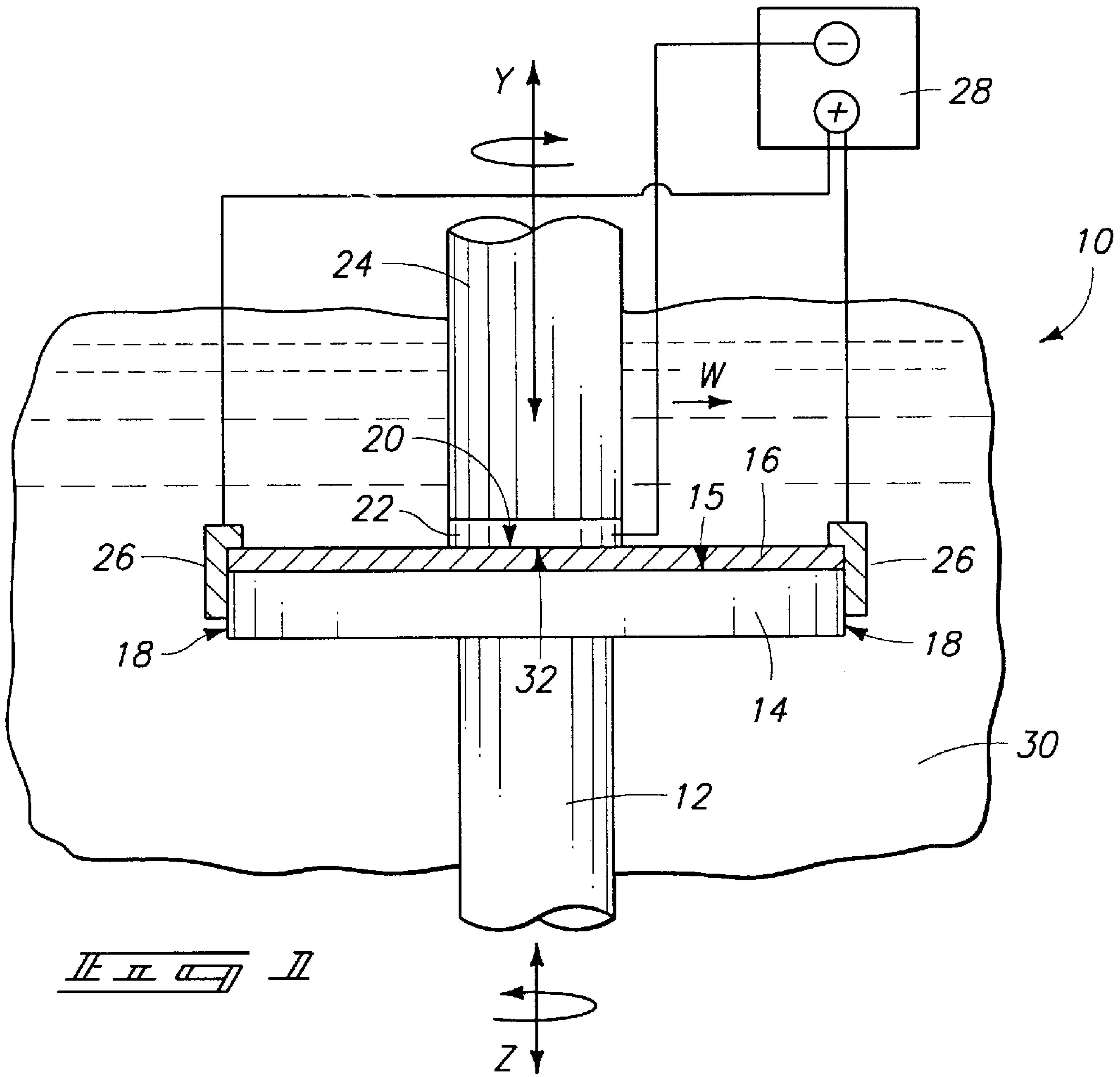



Fig 1

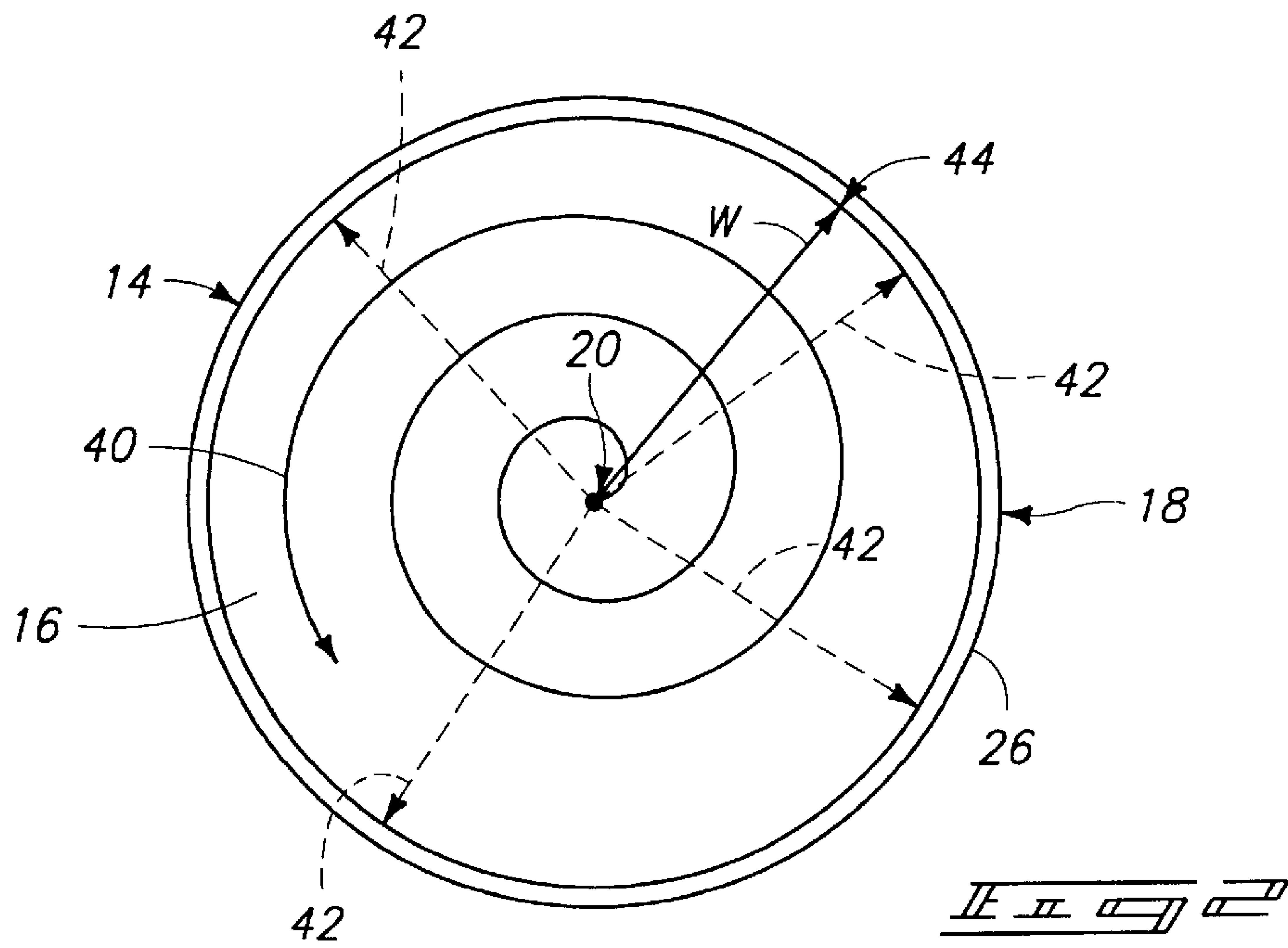
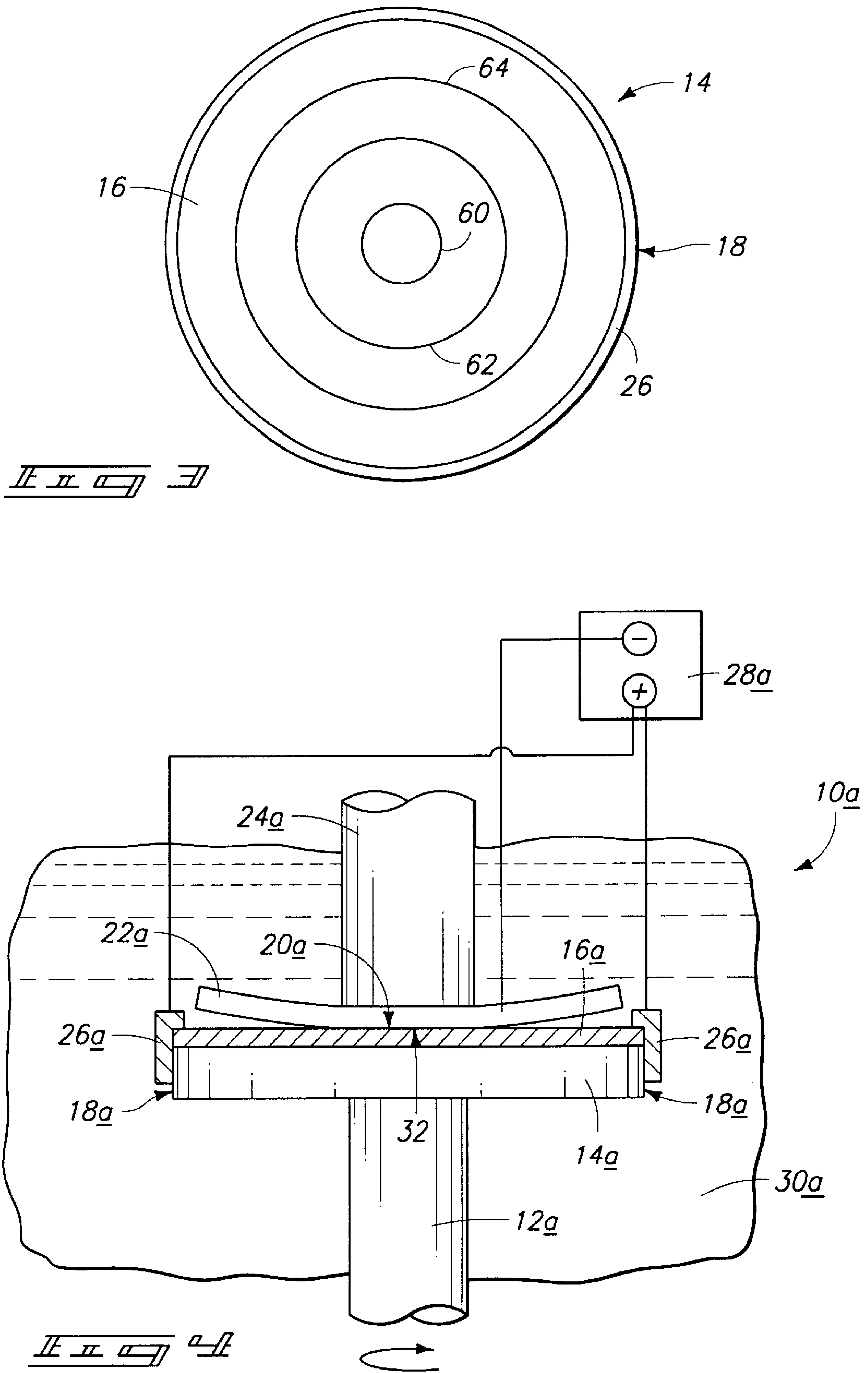



Fig 2


64
14
16
60
18
62
26
Fig 3
28a
10a
24a
22a
20a
16a
26a
26a
18a
18a
32
14a
30a
12a
Fig 4

# SEMICONDUCTOR PROCESSING METHODS OF REMOVING CONDUCTIVE MATERIAL

## TECHNICAL FIELD

The invention pertains to semiconductor processing methods of removing conductive material.

## BACKGROUND OF THE INVENTION

Conductive materials are frequently formed over semiconductive materials during fabrication of semiconductor chips. In typical processing, a circular wafer of semiconductive material is processed to have one or more thin conductive layers formed thereover. The conductive layers can comprise, for example, metal (such as, for example, copper, aluminum, titanium, tantalum, iron, silver, gold, etc.) or other conductive materials (such as, for example, conductively doped polysilicon). The conductive materials can be subsequently planarized by, for example, electrochemical-mechanical planarization. In electrochemical-mechanical planarization, the conductive material is exposed to an electrical circuit which causes at least some of the conductive material to be electrochemically removed and the material is simultaneously exposed to polishing conditions. The polishing conditions enhance removal of the conductive material and planarize a surface of any remaining conductive material. The polishing can be accomplished by, for example, abrasively removing the conductive material with a polishing pad and polishing slurry.

A difficulty associated with electrochemical-mechanical planarization processes can occur in attempting to maintain a circuit through a conductive material during a simultaneous electrochemical removal and polishing process. It is typical to utilize some portions of the conductive material for carrying current to other portions during the electrochemical removal. For instance, peripheral edges of the conductive material can be connected to a cathode terminal of a power source, a polishing pad connected to an anode terminal of the power source, and the conductive material utilized to complete a circuit between the anode and cathode terminals. A problem which can occur as portions of the conductive material are removed is that such can break an electrical connection to other portions of the conductive material. The breakage of the electrical connection can slow or stop electrochemical removal of such other portions of the conductive material.

In particularly problematic instances, some portions of conductive material will be entirely removed from around other portions of conductive material to leave such other portions as islands surrounded by electrically insulative materials. Such islands will thus have no electrical connection between the anode and cathode, and will not be subjected to electrochemical removal conditions. Accordingly, the removal of the islands will occur entirely through mechanical polishing and will be slowed relative to removal of conductive materials exposed to both electrochemical removal and mechanical polishing. Accordingly, there will be non-homogeneous removal of conductive materials from over a surface of a wafer.

It would be desirable to develop methods of electrochemical removal that avoided some or all of the above-discussed problems.

## SUMMARY OF THE INVENTION

In one aspect, the invention encompasses a semiconductive processing method of electrochemical-mechanical



removing at least some of a conductive material from over a surface of a semiconductor substrate. A cathode is provided at a first location of the wafer, and an anode is provided at a second location of the wafer. The conductive material is polished with a polishing pad polishing surface. The polishing occurs at a region of the conductive material and not at another region. The region where the polishing occurs is defined as a polishing operation location. The polishing operation location is displaced across the surface of the substrate from said second location of the substrate toward said first location of the substrate. The polishing operation location is not displaced from said first location toward said second location when the polishing operation location is between the first and second locations.

In another aspect, the invention encompasses a semiconductor processing method of removing at least some of a conductive material from over a surface of a semiconductive material wafer. A polishing pad is displaced across an upper surface of the wafer from a central region of the wafer toward a periphery of the wafer, and is not displaced from the periphery to the central region.

In yet another aspect, the invention encompasses a method of electrochemically removing at least some of a conductive material from over a surface of a circular semiconductive material wafer which comprises radially displacing a polishing pad across the surface of the wafer. The radial displacing occurs only outwardly from a central region of the wafer and not inwardly toward the central region.

## BRIEF DESCRIPTION OF THE DRAWINGS

Preferred embodiments of the invention are described below with reference to the following accompanying drawings.

FIG. **1** is a diagrammatic, fragmentary, cross-sectional sideview of an apparatus utilized in accordance with a method of the present invention.

FIG. **2** is a diagrammatic top view of a semiconductive material wafer processed in accordance with a method of the present invention.

FIG. **3** is a diagrammatic top view of a semiconductive material wafer processed in accordance with a method of the present invention and shown alternatively to the view of FIG. **2**.

FIG. **4** is a diagrammatic, fragmentary, cross-sectional sideview of an apparatus utilized for processing a semiconductive material wafer in accordance with a second embodiment method of the present invention.

## DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENTS

This disclosure of the invention is submitted in furtherance of the constitutional purposes of the U.S. Patent Laws "to promote the progress of science and useful arts" (Article 1, Section 8).

A process of the present invention is described with reference to apparatus **10** of FIG. **1**. Apparatus **10** comprises a support structure **12** having a semiconductor substrate **14** supported thereby. Substrate **14** can comprise, for example, a monocrystalline silicon wafer. To aid in interpretation of the claims that follow, the terms "semiconductive substrate" and "semiconductor substrate" are defined to mean any construction comprising semiconductive material, including, but not limited to, bulk semiconductive materials such as a semiconductive wafer (either alone or in assem-

blies comprising other materials thereon), and semiconductive material layers (either alone or in assemblies comprising other materials). The term "substrate" refers to any supporting structure, including, but not limited to, the semiconductive substrates described above.

Substrate **14** has an upper surface **15**. Such surface can comprise, for example, a surface of a semiconductive material wafer, or can comprise a surface of a material formed over a semiconductive material wafer. For instance, surface **15** can comprise a surface of an insulative material formed over a stack of circuit devices associated with a semiconductive material wafer.

A conductive material **16** is formed over upper surface **15** of substrate **14**. Conductive material **16** can comprise, for example, a metal and/or conductively-doped silicon.

Substrate **14** has an outer peripheral edge **18** and a central inner region **20**. A polishing pad **22** is provided over central region **20** of substrate **14**. Polishing pad **22** is sized to extend over only a central portion of conductive material **16**, and to leave peripheral portions uncovered. Polishing pad **22** is supported by a support structure **24** which is configured to enable rotation of pad **22** about an axis "Y".

Electrical connections **26** are provided along outer periphery **18** of substrate **14** and electrically contact conductive material **16**. Electrical connections **26** are connected to a power source **28** which is also connected to polishing pad **22**. Power source **28** forms a circuit which extends between polishing pad **22** and electrical connections **26** through conductive material **16**, and which utilizes polishing pad **22** as an anode and connections **26** as a cathode. An electrolytic bath **30** is provided over conductive material **16** and between polishing bath **22** and electrical connections **26** to complete the electrical circuit. Electrolytic bath **30** can comprise, for example, an aqueous solution having salts dissolved therein. Bath **30** can also comprises abrasive particles for utilization as polishing slurry during polishing of conductive material **16** with polishing pad **22**.

Although the embodiment of FIG. **1** shows electrolyte as being provided by a bath **30**, it is to be understood that the electrolyte can be provided only over surface **16** by, for example, flowing a stream of electrolyte onto surface **16**. Such stream could be flowed, for example, through a porous polishing pad **22**, or alternatively through a tube provided over surface **16** and configured to allow the electrolyte to flow across surface **16** and under pad **22**. Also, a polishing slurry could be provided by flowing a stream of slurry over surface **16**, rather than as material within a bath.

Support **12** is configured to spin about an axis "Z" and to thereby spin substrate **14** and conductive material **16** relative to polishing pad **22**. Polishing pad **22** comprises a surface **32** configured to abrasively remove material **16** as the surface is moved relative to material **16**. In particular embodiments, the abrasive action of surface **32** results from interaction of surface **32** on a polishing slurry. In other embodiments, the abrasive action results from contact of surface **32** directly against material **16**. Regardless of whether surface **32** contacts material **16** directly and/or through a polishing slurry, the spinning of material **16** relative to polishing pad **22** creates an abrasive action on material **16** which causes removal of at least some of material **16**. Since polishing pad **22** is sized to extend over only a portion of conductive material **16**, polishing surface **32** has a smaller surface area than does material **16**.

Although both pad **22** and substrate **14** are shown being rotated, it is to be understood that the invention encompasses other embodiments wherein only one of pad **22** and substrate **14** is rotated. Also, although pad **22** is shown being rotated in a counter-rotary manner relative to the rotation of substrate **14**, it is to be understood that the invention encompasses other embodiments wherein the pad and substrate rotate in a common direction relative to one another.

An electric current is provided within material **16** from power source **28** during the polishing of the material with pad **22**. Such electric current causes electrochemical removal of conductive material **16**, and thus enhances removal of material **16** relative to the removal which would occur by polishing action alone.

After at least some of conductive material **16** is removed from over central region **20** of substrate **14**, pad **22** is displaced outwardly in direction "W" relative to substrate **14**. Cathode **26** can be considered as being at a first location of substrate **14** and central region **20** can be considered a second location of substrate **14**, and the displacement of pad **22** along direction "W" can thus be considered a movement of polishing surface **32** from the first location of substrate **14** toward the second location. Preferably, polishing pad **22** is displaced only from the second location toward the first location, and not in the reverse direction. In such preferred embodiment, conductive material **16** is removed from over a central location of substrate **14** prior to removing the conductive material from over outer regions of substrate **14**. Thus, a circuit extending between cathode **26** and the anode of pad **22** through conductive material **16** can remain complete during removal of the conductive material **16**. Specifically, since the inner (i.e., more central) portions of conductive material **16** are removed prior to removing outer portions of conductive material **16**, and since pad **22** is not moved back over a more central region of conductive material **16** after removing an outer region of conductive material **16**, a bridge of conductive material **16** can always remain between pad surface **32** and cathode **26** to maintain electrical conductivity between cathode **26** and pad surface **32** during removal of conductive material **16**. Such can alleviate prior art problems discussed above in the "Background" section of this disclosure.

It is noted that although cathode **26** is shown at an outer periphery of substrate **14** and the anode is shown starting at a central region of substrate **14**, the relative positions of the cathode and anode can be reversed. Also, it is noted that cathode **26** can be a single electrode extending entirely around a periphery of substrate **14**, or can comprise a plurality of electrode segments spaced around periphery **18** of substrate **14**. It is additionally noted that although polishing pad **22** is shown starting at a central location of substrate **14**, it is to be understood that the polishing pad could start at a different location of substrate **14**, provided that in a preferred embodiment the pad worked from the starting location toward the cathode, and was not worked back toward the starting location after it had left the starting location.

FIG. **2** shows a top view of substrate **14**, and shows electrode **26** as a continuous electrode extending around substrate **14**. FIG. **2** also shows an exemplary path **40** for polishing pad **22** (FIG. **1**). The pad starts at about central region **20** and spirals outwardly from central region **20** toward periphery **18** of substrate **14**. The shown substrate **14** is circular and has radii **42** extending outwardly from a central location. The spiral path of the polishing pad moves the pad only outwardly along radii **42**, and not inwardly. In other words, the polishing pad is moved only from central location **20** outwardly toward periphery **18**, and not inwardly back toward central location **20**. A term "polishing operation location" is utilized in this document to refer to

locations wherein polishing is actively occurring. The movement of polishing pad **22** moves the polishing operation locations across substrate **14** in the spiral pattern **40**.

Direction "W" of FIG. **1** is shown in FIG. **2** to illustrate that the spiral path **40** causes the polishing pad to be always moving outward from central location **20** toward a point **44** on periphery **18** along direction "W" whenever the pad is between central location **20** and the location corresponding to point **44**. It is also noted that when polishing pad **22** is not between location **20** and point **44**, the pad does not move along direction "W", but instead moves in other directions which take the pad outwardly from central location **20** toward periphery **18**. It is further noted that the spiral trajectory of path **40** defines concentric rings of travel of the polishing pad, with such concentric rings extending radially outward from central location **20**.

The spiral pattern of FIG. **2** is but one pattern which can be utilized to progress polishing operation locations across a substrate surface. Another pattern which could be utilized is in the form of distinct rings **60**, **62** and **64** shown in FIG. **3**. Note that the more centrally occurring ring **60** would preferably be formed first, followed by ring **62**, and lastly by the most outward ring **64**. Note also that the polishing pad could remain in abrasive contact with a surface of conductive material **16** as the pad moves from one ring to another, or alternatively that the pad could be lifted from conductive material **16** during movement of the pad from one ring to another.

As was discussed above with reference to FIG. **1**, one or both of a polishing pad and a wafer substrate can be rotated during displacement of the pad relative to the wafer substrate. It is to be understood that rotation of either the pad or the substrate is not the same as "displacement" within the present application. Specifically, the term "displacement" is defined to refer only to situations in which a polishing operation location is moved across a wafer surface, and not to situations wherein a polishing operation location remains at a same location over a wafer surface while a pad is being rotated or otherwise mechanically agitated. Also, it is to be understood that displacement can occur by moving either a substrate, a polishing pad, or both a substrate and a polishing pad, provided that the net result is movement of the substrate and/or pad relative to the other of the substrate and/or pad. Further, it is to be understood that displacement can occur without moving a polishing pad relative to a substrate, provided that a location of a polishing operation is moved relative to the substrate.

An exemplary apparatus in which a polishing operation location is displaced without displacement of a polishing pad is described with reference to FIG. **4**. In referring to FIG. **4**, similar numbering will be used as was utilized above in describing the apparatus of FIG. **1**, with the suffix "a" used to indicate structures shown in FIG. **4**.

FIG. **4** shows an apparatus **10***a* comprising a substrate holder **12***a* and a substrate **14***a* supported by holder **12***a*. A conductive material **16***a* is formed over substrate **14***a* and extends across an upper surface of substrate **14***a*. Substrate **14***a* has a central region **20***a* and a peripheral region **18***a*, and comprises at least one electrode **26***a* connected to conductive material **16***a* along periphery **18***a*. A flexible-material polishing pad **22***a* is provided over conductive material **16***a*. A narrow structure **24***a* (shown as a post) is provided over a location of pad **22***a* and pushes a region of pad **22***a* against conductive material **16***a*. Pad **22***a* is electrically connected to a power source **28***a*, which in turn is connected to electrode **26***a*.

In operation, post **24***a* is utilized to press a portion of large pad **22***a* against a region of conductive material **26***a*, and subsequently substrate **14***a* is rotated relative to pad **22***a* to cause abrasion of material **26***a* in a location pressed against pad **22***a*. Also, power source **28***a* is utilized to provide current through conductive material **16***a* during rotation of substrate **14***a*, and thus to facilitate electrochemical removal of material **16***a* in conjunction with the abrasive polishing.

Pad **22***a* can be supported by post **24***a* such that the pad and post are moved over conductive material **16***a* in, for example, a spiral pattern similar to that shown in FIG. **2**. Alternatively, pad **22***a* can be separately supported so that the pad remains in a fixed location and post **24***a* is displaced over the pad to cause different portions of the pad to be pushed against spinning substrate **14***a*. Post **24***a* could be moved, for example, in a spiral pattern such as that shown in FIG. **2**. In embodiments in which pad **22***a* remains stationary during the movement of post **24***a*, a location of a polishing operation is displaced relative to substrate **14***a* by displacement of post **24***a*, and without displacement of polishing pad **22***a*. The peripheral edges of pad **22***a* are shown raised relative to the center of pad **22***a*. Such configuration can be achieved by utilizing a pad material having an inherent flex of its peripheral edges relative to its center region, or by attaching one or more support structures (not shown) to the peripheral edges of the pad to raise the edges. Alternatively, the pad can be formed of a flexible material which lays flat across surface **16***a*, but which is in non-abrasive contact with the surface in regions which are not pressed between post **24***a* and surface **16***a*.

It is noted that in the above-described embodiments of FIGS. **1** and **4** only a portion of conductive material **16** is exposed to abrasive polishing at any given time during an electrochemical polishing process. Accordingly, some portions of a conductive material (**16** or **16***a*) are in abrasive contact with a polishing pad (**22** or **22***a*), and other portions are not in such abrasive contact during an electrochemical polishing process. As the polishing process progresses, the portions which had not been in abrasive contact become in abrasive contact while the portions that had been in abrasive contact are no longer in abrasive contact with the polishing pad. Preferably, once a portion progresses from being in abrasive contact with a polishing pad to not being in abrasive contact with the polishing pad, it is no longer exposed to electrochemical polishing conditions during the remainder of the electrochemical polishing process.

The above-described electrochemical polishing processes can be followed by conventional chemical-mechanical polishing processes to buff a substrate after the electrochemical polishing. The chemical-mechanical polishing comprises polishing with a polishing pad and slurry, and is not electrochemical polishing.

In compliance with the statute, the invention has been described in language more or less specific as to structural and methodical features. It is to be understood, however, that the invention is not limited to the specific features shown and described, since the means herein disclosed comprise preferred forms of putting the invention into effect. The invention is, therefore, claimed in any of its forms or modifications within the proper scope of the appended claims appropriately interpreted in accordance with the doctrine of equivalents.

What is claimed is:

**1**. A semiconductor processing method of electrochemical-mechanical removing at least some of a conductive material from over an upper surface of a semiconductor substrate comprising displacing a polishing

operation location across the upper surface of the substrate from a central region of the substrate toward a periphery of the substrate and not displacing the polishing operation location from the periphery to the central region.

**2**. The method of claim **1** wherein the polishing operation location is defined by a location of a polishing pad relative to a surface of the substrate, and further comprising rotating the polishing pad separately from the displacement.

**3**. The method of claim **2** wherein an electrical circuit is provided through at least a portion of the conductive material during the removing, the circuit extending between at least one second electrical connection in electrical contact with a polishing surface of the polishing pad and at least one first electrical connection in direct electrical contact with conductive material only at the periphery.

**4**. The method of claim **2** wherein the displacing comprises moving the substrate relative to the polishing pad.

**5**. The method of claim **2** wherein the displacing comprises moving the polishing pad relative to the substrate.

**6**. The method of claim **2** wherein the displacing comprises moving both the polishing pad and the substrate.

**7**. The method of claim **1** further comprising, after the electrochemical-mechanical removing, chemical-mechanical polishing of the substrate utilizing a process that is not electrochemical-mechanical polishing.

**8**. A semiconductor processing method of electrochemical-mechanical removing at least some of a conductive material from over a surface of a circular semiconductive material wafer comprising radially displacing a polishing pad across the surface of the wafer, the radial displacing being only outwardly from a central region of the wafer and not inwardly toward the central region.

**9**. The method of claim **8** wherein the polishing pad is displaced circularly around the central region to define rings which progress increasingly outward toward a periphery of the wafer.

**10**. The method of claim **9** further comprising rotating the polishing pad separately from the displacement.

**11**. A semiconductor processing method of electrochemical-mechanical removing of at least some of a conductive material from over a surface of a semiconductor substrate comprising:

providing a substrate having a conductive material thereover;

providing a cathode at a first location of the substrate;

providing an anode at a second location of the substrate, the anode being associated with a polishing pad polishing surface;

polishing the conductive material with the polishing pad polishing surface, the polishing occurring at a region of the conductive material and not at another region, the region where the polishing occurs being defined as a polishing operation location; and

displacing the polishing operation location across the surface of the substrate from said second location of the substrate toward said first location of the substrate, and not displacing the polishing operation location from said first location toward said second location when the polishing operation location is between the first and second locations.

**12**. The method of claim **11** wherein the second location is more centrally located on the substrate than the first location.

**13**. The method of claim **11** further comprising rotating at least one of the polishing pad and the substrate separately from the displacement.

**14**. The method of claim **11** wherein the polishing pad is pressed between a structure and the substrate, and wherein the displacing the polishing operation location comprises displacing the structure relative to the polishing pad.

**15**. The method of claim **11** wherein the polishing pad only covers a portion of the conductive material, and wherein the displacing the polishing operation location comprises displacing the polishing pad relative to the substrate.

**16**. The method of claim **15** wherein the displacing comprises moving the substrate relative to the polishing pad.

**17**. The method of claim **15** wherein the displacing comprises moving the polishing pad relative to the substrate.

**18**. The method of claim **15** wherein the displacing comprises moving both the polishing pad and the substrate.

**19**. A semiconductor processing method of removing conductive material, comprising:

providing a semiconductor wafer having a conductive material thereover, the wafer comprising an upper surface and an outer periphery around the upper surface, the conductive material extending across the upper surface of the wafer and to about the periphery;

electrochemically removing at least some of the conductive material with a polishing pad having a surface in abrasive contact with only a portion of the conductive material; and

displacing the polishing pad across the upper surface of the wafer during the removing, the displacing being only from a central region of the wafer surface toward the periphery of the wafer.

**20**. The method of claim **19** wherein the polishing pad is displaced circularly around the central region to define rings which progress increasingly outward toward the periphery of the wafer.

**21**. The method of claim **19** further comprising rotating the polishing pad separately from the displacement.

**22**. The method of claim **19** wherein an electrical circuit is provided through at least a portion of the conductive material during the removing, the circuit extending between at least one second electrical connection in electrical contact with a polishing surface of the polishing pad and at least one first electrical connection in direct electrical contact with conductive material only at the periphery.

**23**. A semiconductor processing method of removing conductive material, comprising:

providing a semiconductor wafer having a conductive material thereover, the wafer comprising an upper surface and an outer periphery around the upper surface, the conductive material extending across the upper surface of the wafer and to about the periphery;

electrochemically removing at least some of the conductive material with a polishing pad having a surface in abrasive contact with only a portion of the conductive material, the portion of the conductive material in abrasive contact with the surface being defined as polishing operation location, the polishing pad extending over the conductive material to cover more of the conductive material than the polishing operation location; and

displacing the polishing operation location across the upper surface of the wafer during the removing, the displacing being only from a central region of the wafer surface toward the periphery of the wafer.

**24**. The method of claim **23** wherein the polishing operation location is displaced across the upper surface of the wafer without displacing the polishing pad.

**25**. The method of claim **23** wherein the polishing operation location is displaced circularly around the central region to define rings which progress increasingly outward toward the periphery of the wafer.

**26**. The method of claim **23** further comprising rotating the wafer separately from the displacement.

**27**. The method of claim **23** wherein an electrical circuit is provided through at least a portion of the conductive material during the removing, the circuit extending between at least one second electrical connection in electrical contact with a polishing surface of the polishing pad and at least one first electrical connection in direct electrical contact with conductive material only at the periphery.

**28**. A semiconductor processing method of removing conductive material, comprising:

providing a semiconductor wafer having a conductive material thereover, the conductive material defining a surface area, the surface area having a first portion surrounded by a second portion;

providing a polishing pad surface in abrasive contact with the first portion of the conductive material surface area and not in abrasive contact with the second portion of the conductive material surface area;

providing a circuit that extends across at least some of the first portion of the conductive material surface area to the second portion;

electrochemically removing at least some of the conductive material from the first portion of the surface area by polishing the first portion with the polishing pad while flowing current through the circuit;

after electrochemically removing the at least some of the conductive material from the first portion, displacing the polishing pad relative to the wafer and electrochemically removing at least some of the conductive material from the second portion surrounding the first portion; and

not electrochemically removing conductive material from the first portion after electrochemically removing conductive material from the second portion.

**29**. The method of claim **28** wherein the first portion of the conductive material surface area is more centrally located on the wafer surface than the second portion of the conductive material surface area.

**30**. The method of claim **28** further comprising rotating at least one of the polishing pad and the wafer separately from the displacement.

**31**. The method of claim **28** wherein the displacing comprises moving the wafer relative to the polishing pad.

**32**. The method of claim **28** wherein the displacing comprises moving the polishing pad relative to the wafer.

**33**. The method of claim **28** wherein the displacing comprises moving both the polishing pad and the wafer.

**34**. A semiconductor processing method of electrochemically removing conductive material, comprising:

providing a semiconductor wafer having a conductive material thereover, the conductive material defining a first surface area, the first surface area having a central portion and an outer peripheral portion surrounding the central portion, the outer peripheral portion having an outermost edge;

providing at least one first electrical contact in electrical connection with the outermost edge of only the outer peripheral portion of the conductive material;

providing a polishing pad proximate the central portion of the conductive material, the polishing pad having a polishing surface, the polishing surface defining a second surface area, the second surface area being less than the first surface area;

providing at least one second electrical contact in electrical connection with the polishing surface of the polishing pad, the first and second electrical contacts being in electrical connection through a power source and defining a circuit that extends through the conductive material;

electrochemically removing at least some of the conductive material from the central portion by polishing the wafer with the polishing pad while flowing current through the circuit; and

only after electrochemically removing at least some of the conductive material from the central portion, displacing the polishing pad relative to the wafer to provide the pad proximate the outer peripheral portion of the conductive material and utilizing the polishing pad to electrochemically remove at least some of the conductive material from the peripheral portion, but not displacing the polishing pad from the outer peripheral portion to the central portion.

**35**. The method of claim **34** wherein the displacing comprises moving the polishing pad circularly around the central region to define rings which progress increasingly outward toward the peripheral portion of the wafer.

**36**. The method of claim **34** wherein the displacing comprises moving the wafer relative to the polishing pad.

**37**. The method of claim **34** wherein the displacing comprises moving the polishing pad relative to the wafer.

**38**. The method of claim **34** wherein the displacing comprises moving both the polishing pad and the wafer.

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